

ORDERING INFORMATION

Part Number*	Package	Top Marking	MSL Rating
MP2329CGG	QFN-11 (2mmx2mm)	See Below	1

* For Tape & Reel, add suffix -Z (e.g.: MP2329CGG-Z).

TOP MARKING

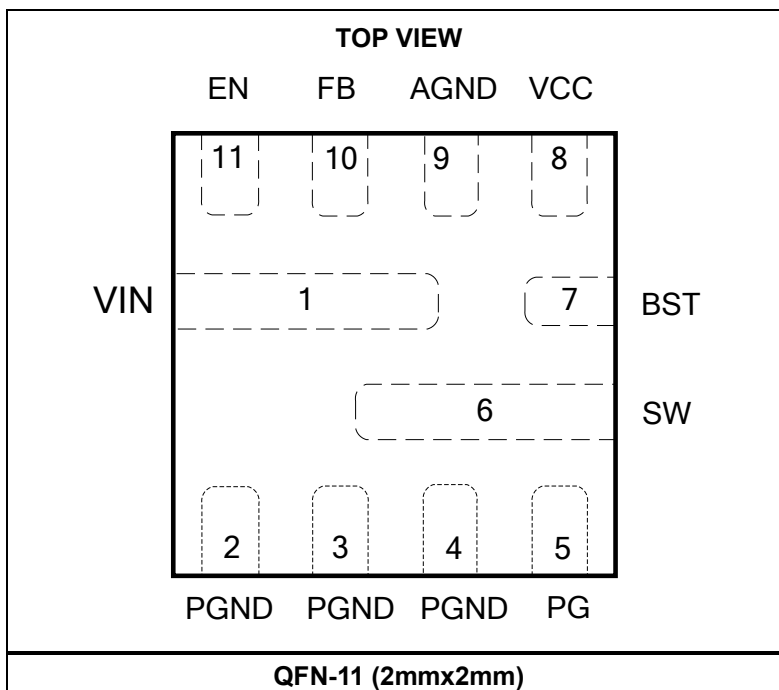
—
HB
Y
LLL

HB: Product code of MP2329CGG

Y: Year code

LLL: Lot number

PACKAGE REFERENCE



PIN FUNCTIONS

PIN #	Name	Description
1	VIN	Supply voltage. VIN supplies power to the internal MOSFET and regulator. The MP2329C operates from a +4.5V to +24V input rail. An input capacitor is needed to decouple the input rail. Connect VIN with wide PCB traces and multiple vias. Apply at least two layers to this input trace.
2 - 4	PGND	Power ground. Connect PGND with wide PCB traces and multiple vias.
5	PG	Power good output. The output of PG is an open drain.
6	SW	Switch output. Connect SW to the inductor and bootstrap capacitor. SW is driven up to VIN by the high-side switch during the on time of the PWM duty cycle. The inductor current drives SW negative during the off time. The on resistance of the low-side switch and the internal diode fixes the negative voltage. Connect SW with wide and short PCB traces. Try to minimize the area of the SW pattern.
7	BST	Bootstrap. Connect a capacitor between SW and BST to form a floating supply across the high-side switch driver.
8	VCC	Internal 3V3 VCC LDO output. VCC powers the driver and control circuits. Decouple VCC with a minimum 1µF ceramic capacitor as close to VCC as possible. X7R or X5R grade dielectric ceramic capacitors are recommended for their stable temperature characteristics.
9	AGND	Signal logic ground. AGND is the Kelvin connection to PGND.
10	FB	Feedback. An external resistor divider from the output to GND tapped to FB sets the output voltage. Place the resistor divider as close to FB as possible. Avoid vias on the FB traces and V _{SEN} trace. Keep the V _{SEN} trace far away from the SW node.
11	EN	Buck enable pin. EN is a digital input that turns the buck regulator on or off. When the power supply of the control circuit is ready, drive EN high to turn on the buck regulator. Drive EN low to turn off the buck regulator. Connect EN to VIN through a resistive voltage divider for automatic start-up. Do not make the EN voltage higher than 4.5V at any time. Do not float EN.

ABSOLUTE MAXIMUM RATINGS (1)

Supply voltage (V _{IN})	26V
V _{SW} (DC)	-1V to V _{IN} + 0.3V
V _{SW} (25ns)	-3.6V to V _{IN} + 4V (2)
V _{BST}	V _{SW} + 4.5V
All other pins	-0.3V to + 4.5V
Continuous power dissipation (T _A = +25°C) (3)(5)	
QFN-11 (2mmx2mm)	3.6W
Junction temperature	150°C
Lead temperature	260°C
Storage temperature	-65°C to +150°C

ESD Rating

Human-body model (HBM)	1.8KV
Charged-device model (CDM)	2KV

Recommended Operating Conditions (4)

Supply voltage (V _{IN})	4.5V to 24V
Output voltage (V _{OUT})	0.6V to 13V
Operating junction temp. (T _J)	-40°C to +125°C

Thermal Resistance

θ_{JA} θ_{JC}

QFN-11 (2mmx2mm)		
EV2329C-G-00A (5)	34	9 °C/W
JESD51-7 (6)	80	16 °C/W

NOTES:

- Exceeding these ratings may damage the device.
- Measured by using differential oscilloscope probe.
- The maximum allowable power dissipation is a function of the maximum junction temperature T_J(MAX), the junction-to-ambient thermal resistance θ_{JA} , and the ambient temperature T_A. The maximum allowable continuous power dissipation at any ambient temperature is calculated by P_D(MAX)=(T_J(MAX)-T_A)/ θ_{JA} . Exceeding the maximum allowable power dissipation produces an excessive die temperature, causing the regulator to go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.
- The device is not guaranteed to function outside of its operating conditions.
- Measured on EV2329C-G-00A, 4-layer PCB, 64mmx64mm.
- The value of θ_{JA} given in this table is only valid for comparison with other packages and cannot be used for design purposes. These values were calculated in accordance with JESD51-7 and simulated on a specified JEDEC board. They do not represent the performance obtained in an actual application.

ELECTRICAL CHARACTERISTICS

$V_{IN} = 12V$, $T_J = -40^{\circ}C$ to $+125^{\circ}C$ ⁽⁷⁾, typical value is tested at $T_J = 25^{\circ}C$, unless otherwise noted.

Parameters	Symbol	Condition	Min	Typ	Max	Units
Supply Current						
Supply current (quiescent)	I_{IN}	$V_{EN} = 3.3V$, $V_{FB} = 0.62V$		105	145	μA
Supply current (shutdown)	I_{IN}	$V_{EN} = 0V$			2	μA
MOSFET						
High-side switch on resistance	HS_{RDS-ON}			36		m Ω
Low-side switch on resistance	LS_{RDS-ON}			12		m Ω
Switch leakage	SW_{LKG}	$V_{EN} = 0V$, $V_{SW} = 0V$		0	5	μA
Current Limit						
Low-side valley current limit	I_{LIMIT_LS}		6	7.5	9	A
Negative current limit	I_{NEG}	$V_{OUT} = 3.3V$, $L_O = 2.2\mu H$	-2	-1.5	-1	A
Switching Frequency and Minimum Off Timer						
Switching frequency	F_S	$V_{IN} = 12V$, $V_{OUT} = 3.3V$	600	700	800	kHz
Minimum on time ⁽⁸⁾	T_{ON_Min}			50		ns
Minimum off time ⁽⁸⁾	T_{OFF_Min}			200		ns
Over-Voltage and Under-Voltage Protection (OVP, UVP)						
OVP threshold	V_{OVP}	V_{FB}	125%	130%	135%	V_{REF}
UVP-1 threshold	V_{UVP}	V_{FB}	70%	75%	80%	V_{REF}
UVP-1 hold off timer ⁽⁸⁾	T_{OC}	$V_{OUT} = 60\% V_{REF}$		32		μs
UVP-2 threshold	V_{UVP}	V_{FB}	45%	50%	55%	V_{REF}
Reference and Soft Start (REF, SS)						
REF voltage	V_{REF}		590	600	610	mV
Soft start time ⁽⁸⁾	T_{SS}		1.1	1.7	2.3	ms
Enable and UVLO (EN, UVLO)						
Enable rising threshold	V_{EN_Rising}		1.15	1.25	1.35	V
Enable hysteresis	V_{EN_HYS}			150		mV
Enable input current	I_{EN}	$V_{EN} = 3.3V$		3.3		μA
VCC UVLO threshold rising	V_{CCVth_R}		3.1	3.3	3.5	V
VCC UVLO threshold hysteresis	V_{CCHYS}			420		mV
VIN UVLO threshold rising	V_{INVth_R}		4.2	4.35	4.48	V
VIN UVLO threshold hysteresis	V_{INHYS}			550		V
VCC Regulator						
VCC voltage	V_{CC}		3.45	3.65	3.85	V
VCC load regulation	V_{CC_Reg}	$I_{VCC} = 5mA$		5		%
Thermal Protection						
Thermal shutdown ⁽⁸⁾	T_{SD}			150		$^{\circ}C$
Thermal shutdown hysteresis ⁽⁸⁾	T_{SD_HYS}			25		$^{\circ}C$

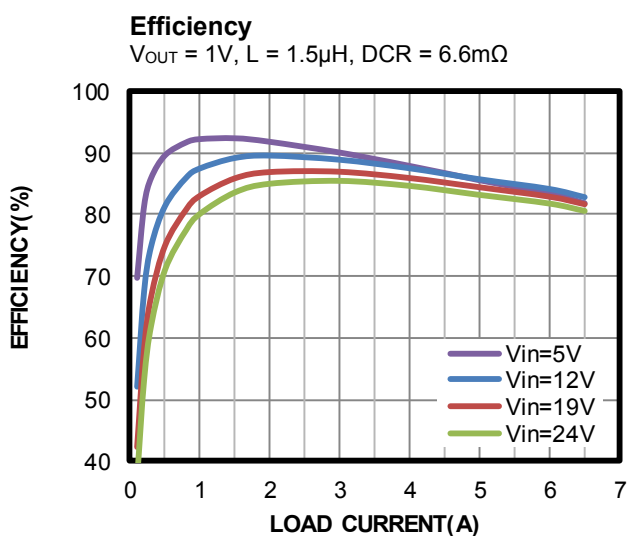
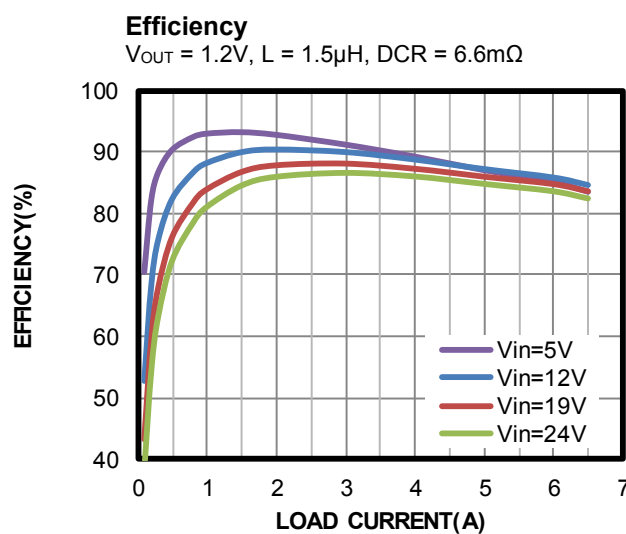
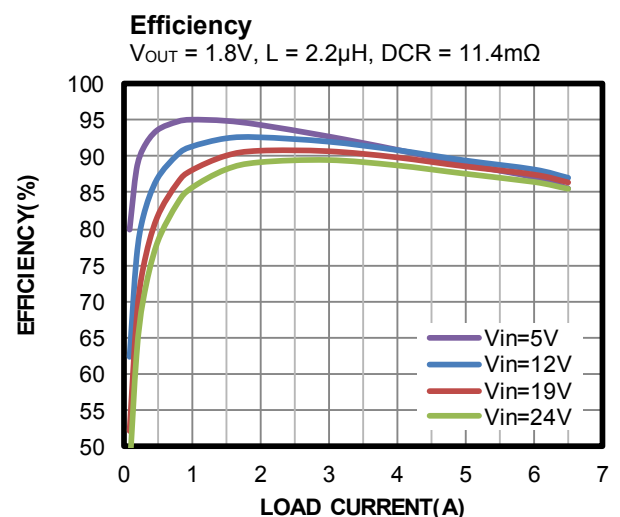
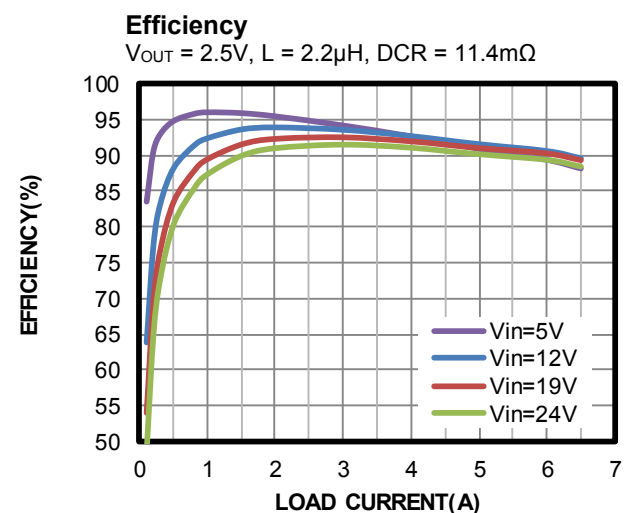
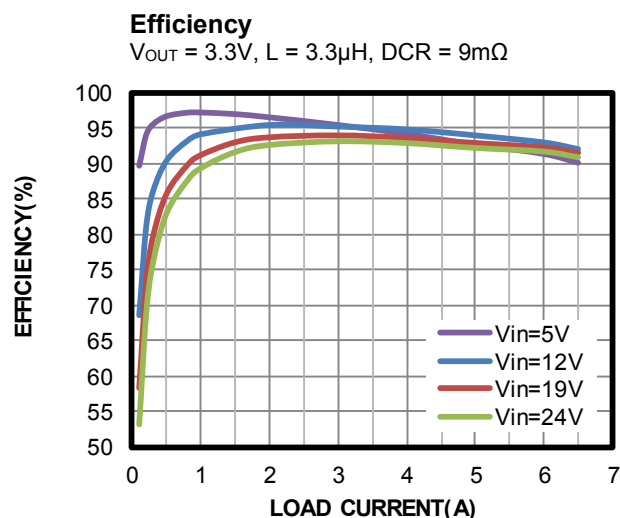
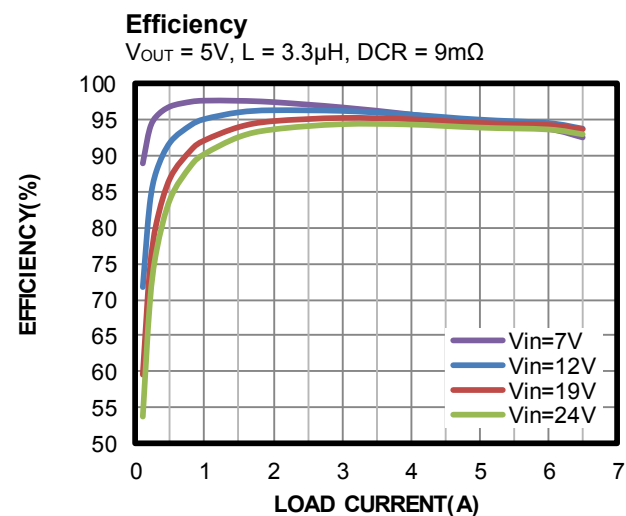
NOTES:

7) Not tested in production. Guaranteed by over-temperature correlation.

8) Guarantee by engineering sample characterization.

TYPICAL CHARACTERISTICS

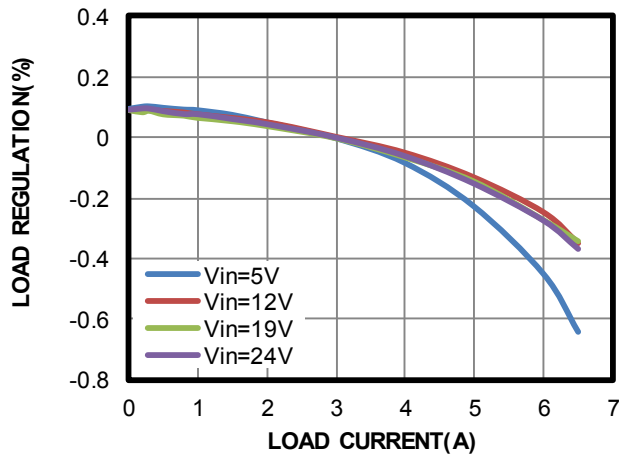
$V_{IN} = 19V$, $V_{OUT} = 3.3V$, $L = 3.3\mu H$, $T_A = +25^\circ C$, unless otherwise noted.



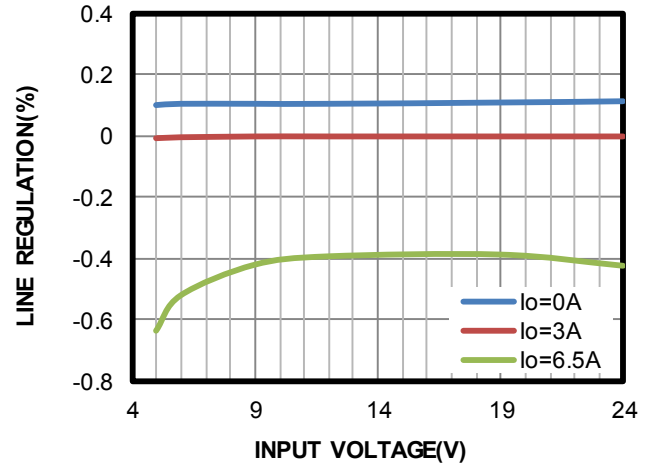
TYPICAL CHARACTERISTICS (continued)

$V_{IN} = 19V$, $V_{OUT} = 3.3V$, $L = 3.3\mu H$, $T_A = +25^\circ C$, unless otherwise noted.

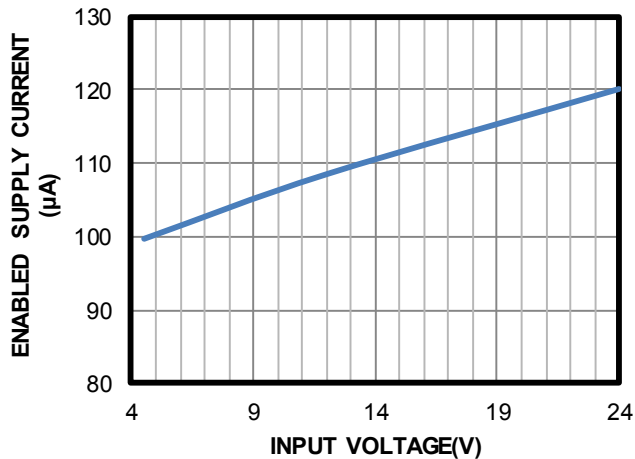
Load Regulation



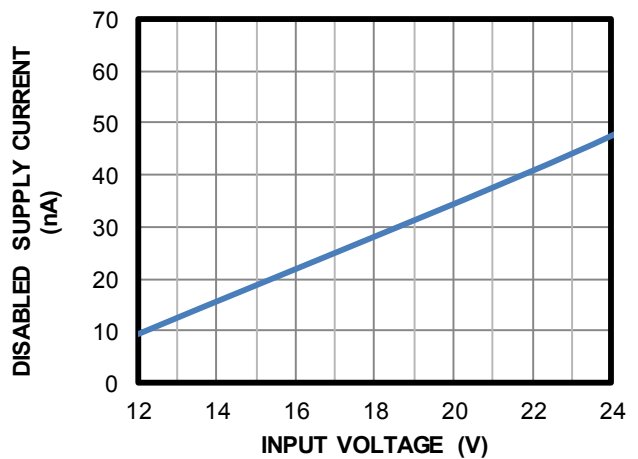
Line Regulation



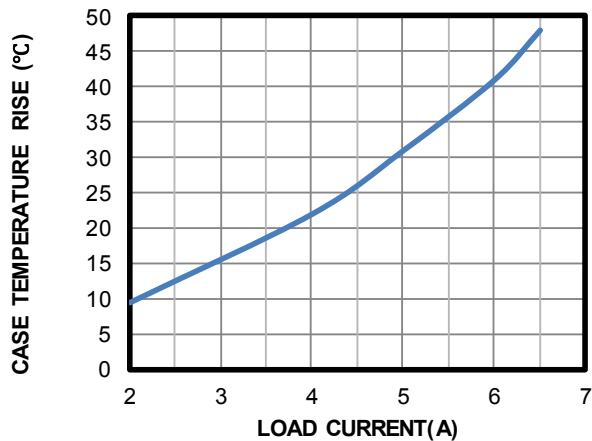
Enabled Supply Current vs. Input Voltage $V_{EN} = 3.3V$, $V_{FB} = 0.62V$



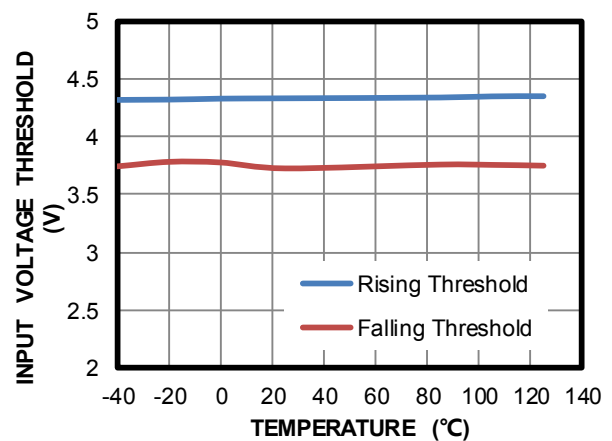
Disabled Supply Current vs. Input Voltage $V_{EN} = 0V$



Case Temperature Rise vs. Load Current $V_{IN} = 19V$, $V_{OUT} = 3.3V$



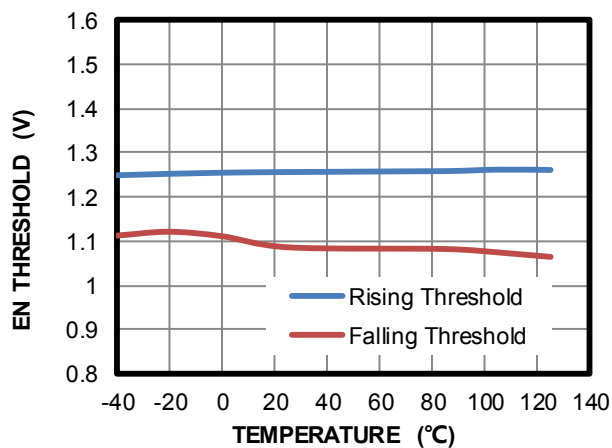
Input Voltage Threshold vs. Temperature



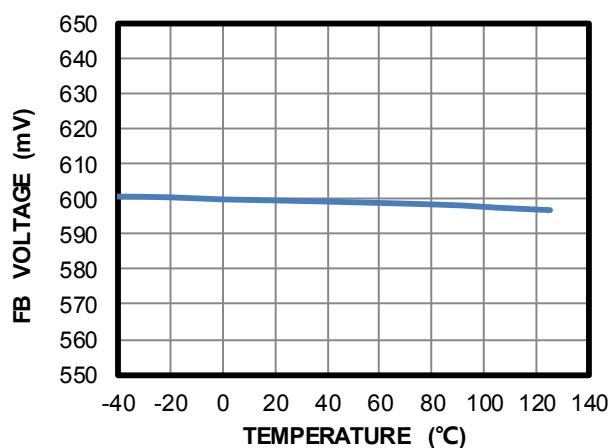
TYPICAL CHARACTERISTICS *(continued)*

$V_{IN} = 19V$, $V_{OUT} = 3.3V$, $L = 3.3\mu H$, $T_A = +25^\circ C$, unless otherwise noted.

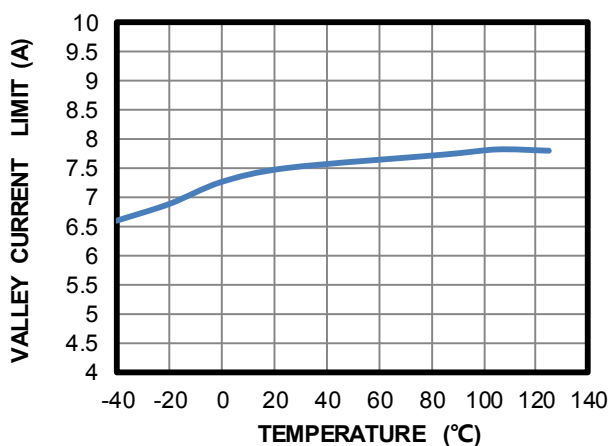
EN Threshold vs. Temperature



FB Voltage vs. Temperature



Valley Current Limit vs. Temperature



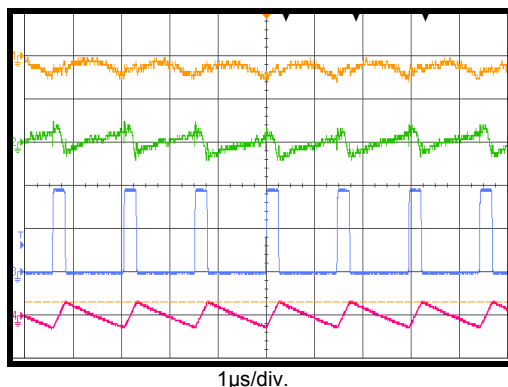
TYPICAL PERFORMANCE CHARACTERISTICS

$V_{IN} = 19V$, $V_{OUT} = 3.3V$, $L = 3.3\mu H$, $T_A = +25^{\circ}C$, unless otherwise noted.

Input/Output Ripple

$I_{OUT} = 0A$

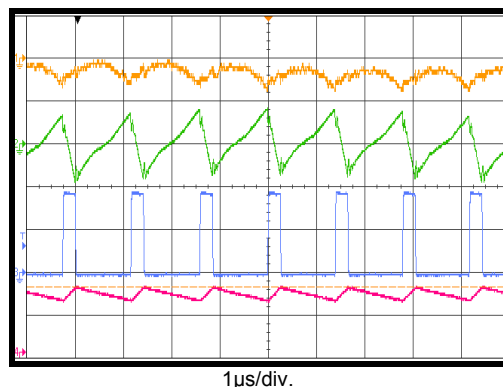
CH1: V_{OUT}/AC
20mV/div.
CH2: V_{IN}/AC
20mV/div.
CH3: V_{SW}
10V/div.
CH4: I_L
2A/div.



Input/Output Ripple

$I_{OUT} = 6.5A$

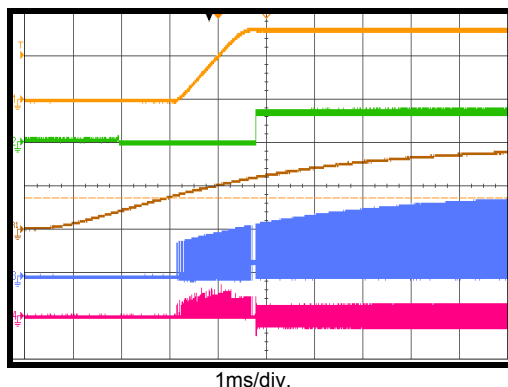
CH1: V_{OUT}/AC
200mV/div.
CH2: V_{IN}/AC
200mV/div.
CH3: V_{SW}
10V/div.
CH4: I_L
5A/div.



Start-Up through Input Voltage

$I_{OUT} = 0A$

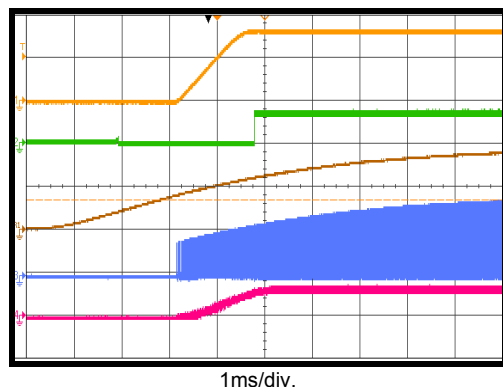
CH1: V_{OUT}
2V/div.
CH2: V_{PG}
5V/div.
R1: V_{IN}
10V/div.
CH3: V_{SW}
10V/div.
CH4: I_L
2A/div.



Start-Up through Input Voltage

$I_{OUT} = 6.5A$

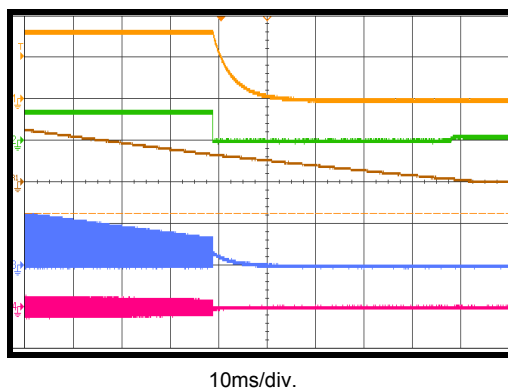
CH1: V_{OUT}
2V/div.
CH2: V_{PG}
5V/div.
R1: V_{IN}
10V/div.
CH3: V_{SW}
10V/div.
CH4: I_L
10A/div.



Shutdown through Input Voltage

$I_{OUT} = 0A$

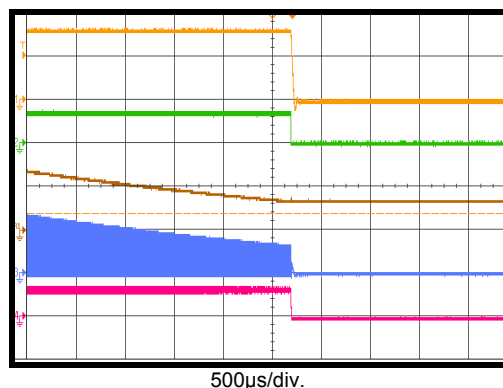
CH1: V_{OUT}
2V/div.
CH2: V_{PG}
5V/div.
R1: V_{IN}
10V/div.
CH3: V_{SW}
10V/div.
CH4: I_L
2A/div.



Shutdown through Input Voltage

$I_{OUT} = 6.5A$

CH1: V_{OUT}
2V/div.
CH2: V_{PG}
5V/div.
R1: V_{IN}
10V/div.
CH3: V_{SW}
10V/div.
CH4: I_L
10A/div.

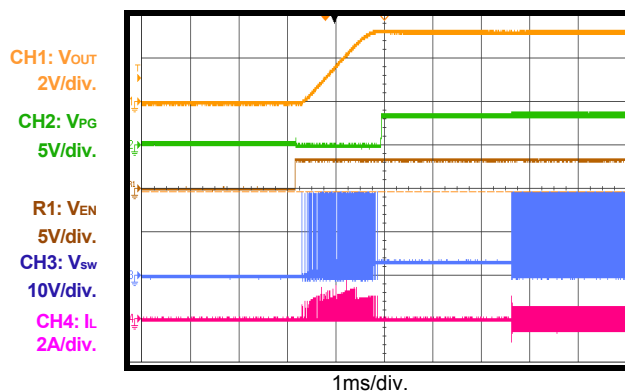


TYPICAL PERFORMANCE CHARACTERISTICS (continued)

$V_{IN} = 19V$, $V_{OUT} = 3.3V$, $L = 3.3\mu H$, $T_A = +25^\circ C$, unless otherwise noted.

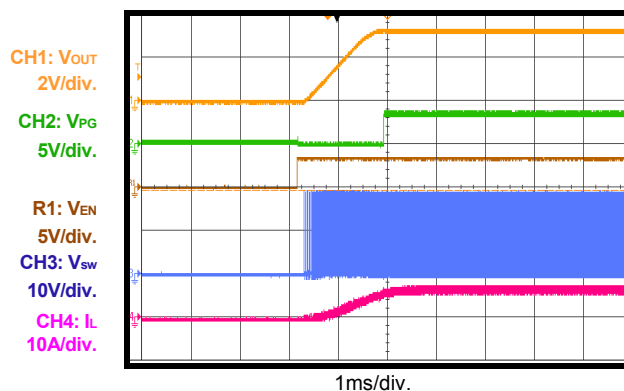
Start-Up through Enable

$I_{OUT} = 0A$



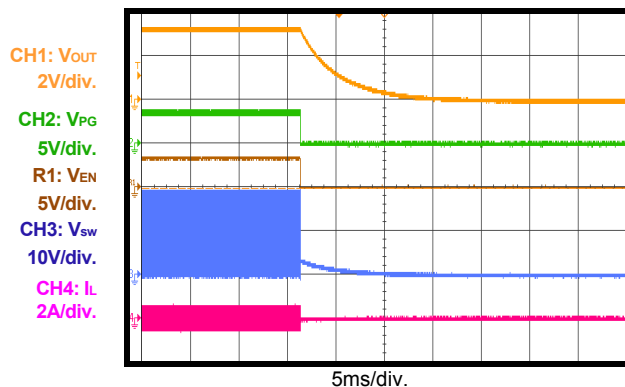
Start-Up through Enable

$I_{OUT} = 6.5A$



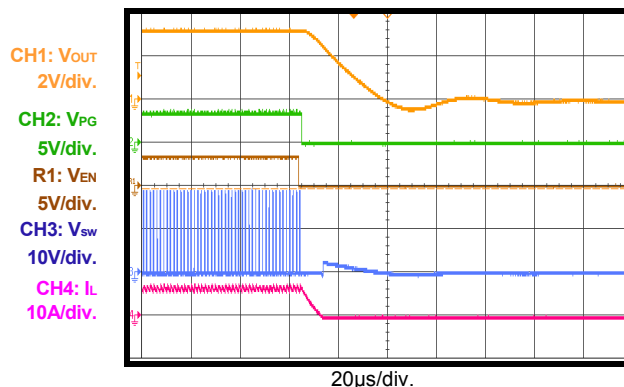
Shutdown through Enable

$I_{OUT} = 0A$



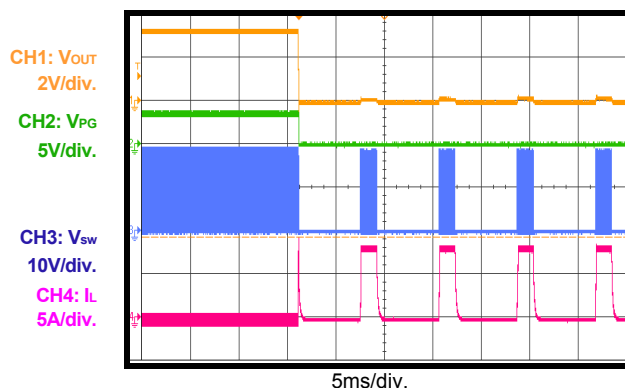
Shutdown through Enable

$I_{OUT} = 6.5A$



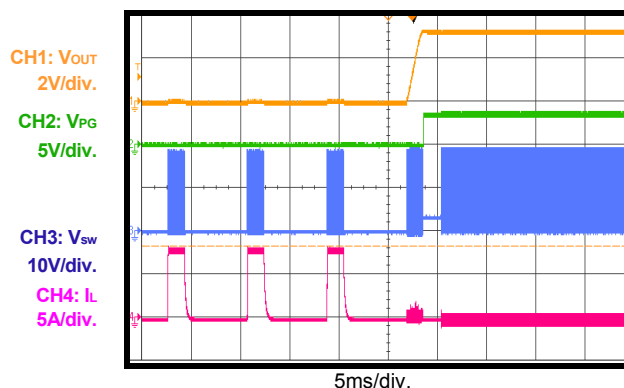
Short-Circuit Entry

$I_{OUT} = 0A$



Short-Circuit Recovery

$I_{OUT} = 0A$



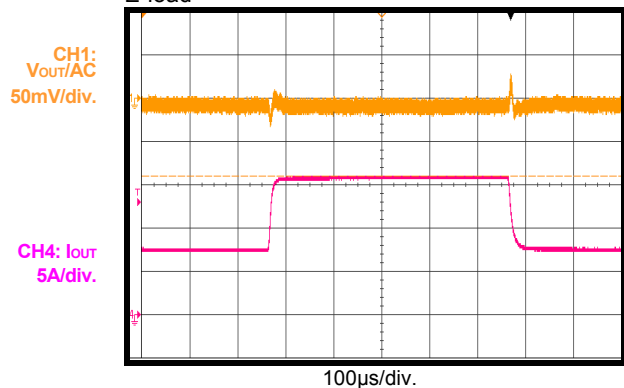
TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

$V_{IN} = 19V$, $V_{OUT} = 3.3V$, $L = 3.3\mu H$, $T_A = +25^\circ C$, unless otherwise noted.

Load Transient

$I_{OUT} = 3 - 6.5A$, slew rate is $2.5A/\mu s$ by CCDH

E-load



BLOCK DIAGRAM

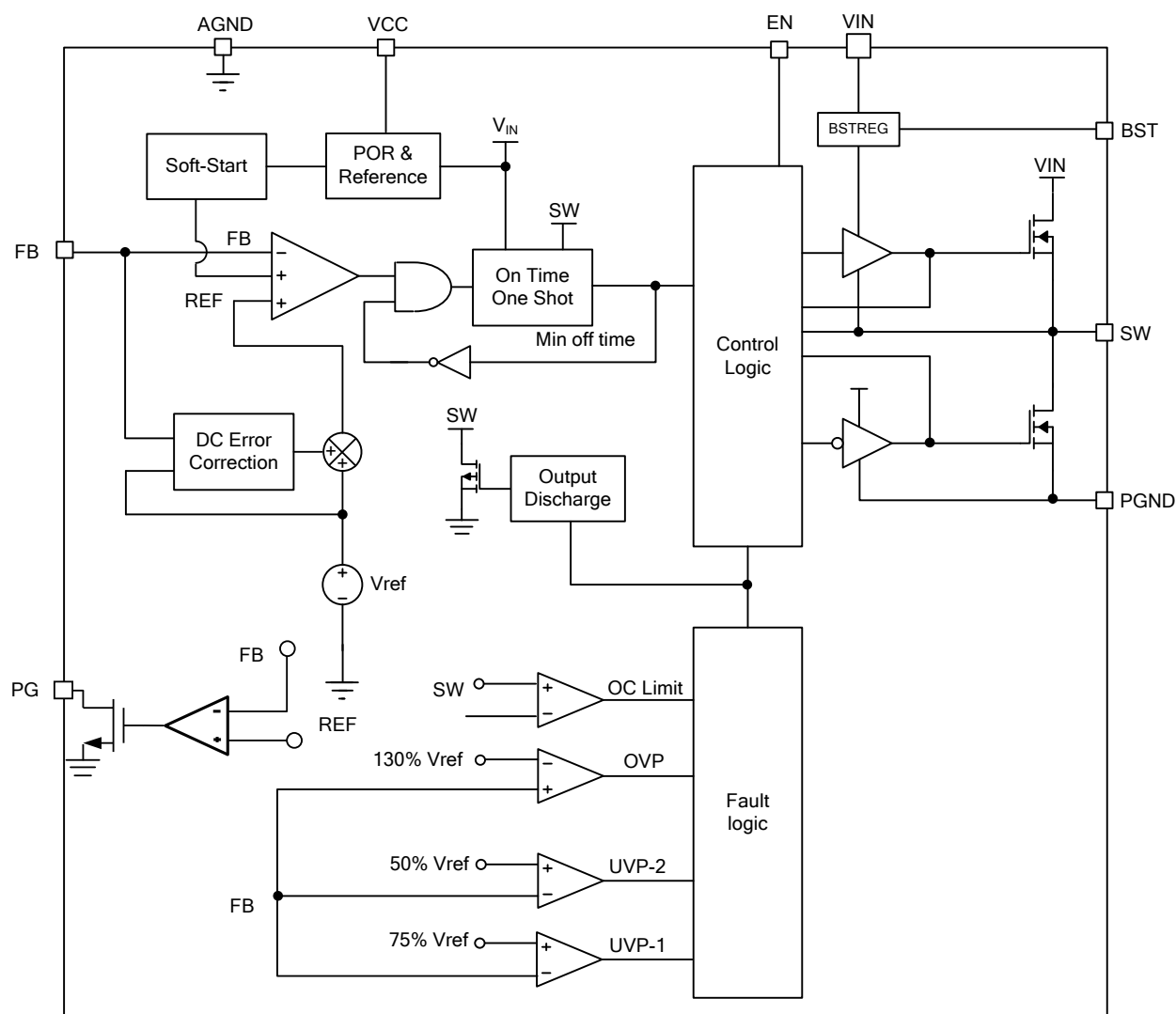


Figure 1: Functional Block Diagram

OPERATION

Pulse-Width Modulation (PWM) Operation

The MP2329C is a fully integrated, synchronous, rectified, step-down, switch-mode converter. Constant-on-time (COT) control is employed to provide fast transient response and easy loop stabilization. At the beginning of each cycle, the high-side MOSFET (HS-FET) is turned on when the feedback voltage (V_{FB}) is below the reference voltage (V_{REF}), which indicates an insufficient output voltage. The on period is determined by the output voltage and input voltage to make the switching frequency fairly constant over the input voltage range.

The MP2329C operates in forced continuous conduction mode (CCM). The LS-FET turns on when the HS-FET is in its off state to minimize conduction loss. There is a dead short between the input and GND if both the HS-FET and LS-FET are turned on at the same time. This is called a shoot-through. To prevent a shoot-through, a dead time is generated internally between the HS-FET off and LS-FET on, or LS-FET off and HS-FET on.

Internal compensation is applied for COT control to provide a more stable operation, even when ceramic capacitors are used as output capacitors. This internal compensation improves jitter performance without affecting the line or load regulation.

Large Duty Cycle Operation

When V_{IN} is below 7V and V_{OUT} is above 4.2V, the MP2329C reduces switching frequency to about 280kHz to support large-duty operation. If V_{OUT} is below 3.9V, the MP2329C returns to the normal switching frequency.

Jitter and FB Ramp

Jitter occurs in both PWM and skip mode when noise in the V_{FB} ripple propagates a delay to the HS-FET driver (see Figure 2 and Figure 3). Jitter can affect system stability with noise immunity proportional to the steepness of V_{FB} 's downward slope. Therefore, the jitter in DCM is usually larger than that in CCM. However, V_{FB} ripple does not affect noise immunity directly.

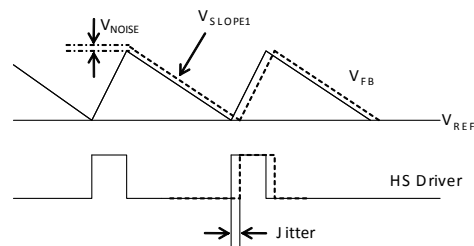


Figure 2: Jitter in PWM Mode

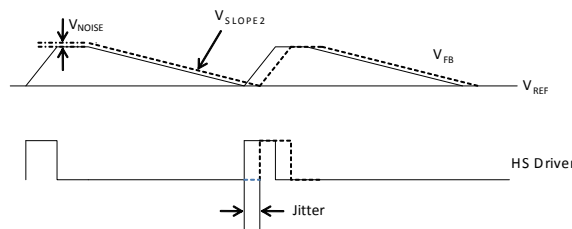


Figure 3: Jitter in Skip Mode

Operating with External Ramp Compensation

The MP2329C is able to support ceramic output capacitors without an external ramp, typically. However, in some cases, the internal ramp may not be enough to stabilize the system, or the jitter is too large. In these cases, external ramp compensation is needed. Refer to the Setting the Output Voltage with External Compensation section on page xx for design steps using external ramp compensation.

Configuring the EN Control

The enable pin (EN) is used to enable or disable the entire chip. Pull EN high to turn on the regulator. Pull EN low to turn off the regulator. Do not float EN.

For automatic start-up, EN can be pulled up to the input voltage through a resistive voltage divider. Choose the values of the pull-up resistor (R_{UP} from V_{IN} to EN) and the pull-down resistor (R_{DOWN} from EN to GND) to determine the automatic start-up voltage with Equation (1):

$$V_{IN-START} = 1.25 \times \frac{R_{UP} + R_{DOWN}}{R_{DOWN}} (V) \quad (1)$$

For example, when $R_{UP} = 150k\Omega$ and $R_{DOWN} = 51k\Omega$, $V_{IN-START}$ is 4.92V.

The EN voltage must not exceed the 4.5V maximum value to avoid damaging the internal circuit.

Power Good (PG)

The power good pin (PG) indicates whether the output voltage is in the normal range compared to the internal reference voltage. PG is an open-drain structure and requires an external pull-up supply. During power-up, the PG output is pulled low. This indicates to the system to remain off and keep the load on the output to a minimum. This helps reduce inrush current during start-up.

When the output voltage is higher than 95% and lower than 115% of internal reference voltage and the soft start is finished, the PG signal is pulled high. When the output voltage is lower than 90% after the soft start finishes, the PG signal remains low. When the output voltage is higher than 115% of the internal reference, PG is switched low. The PG signal rises high again after the output voltage drops below 105% of the internal V_{REF} . The PG output is pulled low when the EN under-voltage lockout (UVLO), input UVLO, over-current protection (OCP), or over-temperature protection (OTP) is triggered.

Soft Start (SS)

The MP2329C employs a soft start (SS) mechanism to ensure a smooth output during power-up. When EN rises high, the internal V_{REF} ramps up gradually, and the output voltage ramps up smoothly as well. Once V_{REF} reaches the target value, the soft start finishes, and the device enters steady-state operation.

If the output is pre-biased to a certain voltage during start-up, the IC disables the switching of both the high-side and low-side switches until the voltage on the internal reference exceeds the sensed output voltage at the FB node.

Over-Current Limit

The MP2329C has a cycle-by-cycle over-current limiting control. The current-limit circuit employs a valley current-sensing algorithm. The MP2329C uses the $R_{DS(ON)}$ of the LS-FET as a current-sensing element. If the magnitude of the current-sense signal is above the current-limit threshold, the PWM is not allowed to initiate a new cycle, even if FB is lower than REF. Figure 4 shows the detailed operation of the valley-current limit.

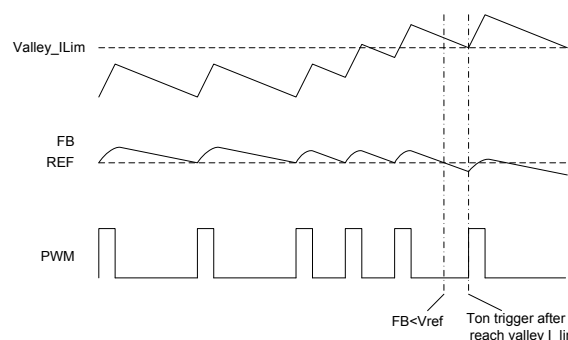


Figure 4: Valley Current-Limit Control

Since the comparison is done during the low-side on state, the OC trip level sets the valley level of the inductor current. The maximum load current at the over-current threshold (I_{OC}) can be calculated with Equation (2):

$$I_{OC} = I_{\text{limit}} + \frac{\Delta I_{\text{inductor}}}{2} \quad (2)$$

The OCL itself limits the inductor current and does not latch off. In an over-current condition, the current to the load exceeds the current to the output capacitor, making the output voltage fall off. Eventually, the current ends up crossing the under-voltage protection (UVP) threshold, and MP2329C enters hiccup protection mode.

Over-/Under-Voltage Protection (OVP/UVP)

The MP2329C monitors a resistor-divided feedback voltage to detect over- and under-voltage conditions. When V_{FB} rises higher than 130% of the target voltage, the over-voltage protection (OVP) comparator output goes high, and the circuit latches as the HS-FET driver turns, off and the LS-FET turn on and acts as a current source.

When V_{FB} is between 50% and 75% of V_{REF} , the UVP-1 comparator output goes high, and the MP2329C enters hiccup mode if V_{FB} remains in this range for about 32 μ s. The LS-FET remains on until the inductor current drops to zero. During this period, the valley current limit helps control the inductor current.

When V_{FB} drops below 50% of V_{REF} , the UVP-2 comparator output goes high, and the MP2329C enters hiccup mode directly after the comparator and logic delay.

UVLO Protection

The MP2329C has two types of UVLO protection: VCC UVLO and V_{IN} UVLO. The MP2329C starts up only when both VCC and V_{IN} exceed their respective UVLO threshold. The MP2329C shuts down when either VCC is lower than the UVLO falling threshold voltage or V_{IN} is lower than the V_{IN} falling threshold. These are both non-latch off protections.

If an application requires a higher UVLO, use EN as shown in Figure 5 to adjust the input voltage UVLO using two external resistors.

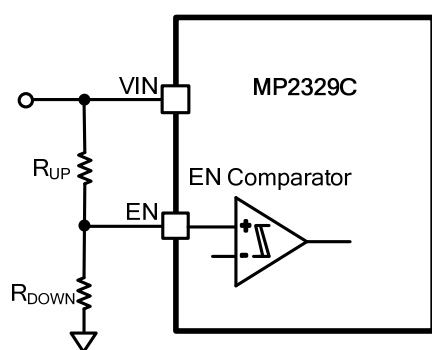


Figure 5: Adjustable UVLO

Thermal Shutdown

The MP2329C has a thermal shutdown function. The junction temperature of the IC is monitored internally. If the junction temperature exceeds the threshold value (typically 150°C), the converter shuts off. This is a non-latch protection. There is a hysteresis of about 25°C. Once the junction temperature drops to about 125°C, a soft start is initiated.

Output Discharge

The MP2329C discharges the output when the controller is turned off by a protection function (UVP, OCP, OVP, UVLO, thermal shutdown). The discharge resistor on the output is 6Ω, typically.

APPLICATION INFORMATION

Setting the Output Voltage without External Compensation

The MP2329C does not require ramp compensation for applications using POSCAP or ceramic caps as output capacitors. The output voltage is set by feedback resistors R1 and R2 (see Figure 6).

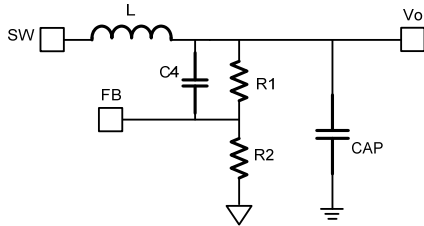


Figure 6: Simplified Circuit without an External Ramp

First, choose a value for R2. R2 should be chosen reasonably, since a small R2 leads to considerable quiescent current loss, but a large R2 makes FB noise-sensitive. Set R2 to be between 5 - 100kΩ, using a comparatively larger R2 when V_{OUT} is low and a smaller R2 when V_{OUT} is high. Considering the output ripple, R1 can be determined with Equation (3):

$$R_1 = \frac{V_{OUT} - V_{REF}}{V_{REF}} \cdot R_2 \quad (3)$$

C4 acts as a feed-forward cap to improve the transient and can be set in the range of 100pF - 1nF. A larger C4 leads to better transient but more noise sensitivity.

Table 1 lists the recommended resistor values for common output voltages.

Table 1: Parameters Selection for Common Output Voltages⁽⁹⁾

V _{OUT} (V)	R1 (kΩ)	R2 (kΩ)	C4 (pF)	L (μH)
5	40.2	5.49	33	3.3
3.3	40.2	8.87	33	3.3
2.5	40.2	12.7	33	2.2
1.8	40.2	20	33	2.2
1.5	40.2	26.7	33	1.5
1.2	40.2	40.2	33	1.5
1	40.2	60.4	33	1.5

NOTE:

9) For additional component parameters, please refer to the Typical Application Circuits on page 18 to page 20.

Setting the Output Voltage with External Compensation

If the system is not stable enough or the jitter is too large when ceramic capacitors are used in the output, an external voltage ramp should be added to FB through resistor R4 and capacitor C4. Since an internal ramp has already been added in the system, a 1MΩ (R4), 220pF (C4) ramp is sufficient for the ramp, typically.

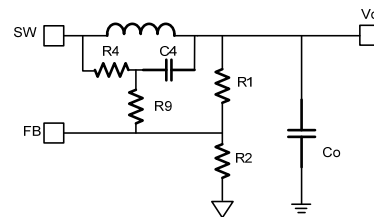


Figure 7: Simplified Circuit with External Ramp

The output voltage is influenced by R4 in addition to the R1 and R2 divider shown in Figure 7. R2 should be chosen reasonably, since a small R2 leads to considerable quiescent current loss while a large R2 makes FB noise-sensitive. Set R2 to be between 5 - 100kΩ, using a comparatively larger R2 when V_{OUT} is low and a smaller R2 when V_{OUT} is high. R1 can then be determined with Equation (4):

$$R_1 = \frac{1}{\frac{V_{REF}}{V_{OUT} - V_{REF}} - \frac{R_2}{R_4}} \cdot R_2 \quad (4)$$

Usually, R9 is set to 0Ω. To get a pole for better noise immunity, R9 can also be set using Equation (5):

$$R_9 = \frac{1}{2\pi \times C_4 \times 2F_{SW}} \quad (5)$$

R9 should be set in the range of 100Ω to 1kΩ to reduce its influence on the ramp.

Selecting the Input Capacitor

The input current to the step-down converter is discontinuous and therefore requires a capacitor to supply AC current to the step-down converter while maintaining the DC input voltage. Ceramic capacitors are recommended for the best performance and should be placed as close to VIN as possible. Capacitors with X5R and X7R ceramic dielectrics are

recommended since they are fairly stable with temperature fluctuations.

The capacitors must also have a ripple current rating greater than the maximum input ripple current of the converter. The input ripple current can be estimated with Equation (6):

$$I_{CIN} = I_{OUT} \times \sqrt{\frac{V_{OUT}}{V_{IN}} \times (1 - \frac{V_{OUT}}{V_{IN}})} \quad (6)$$

The worst-case condition occurs at $V_{IN} = 2V_{OUT}$, shown in Equation (7):

$$I_{CIN} = \frac{I_{OUT}}{2} \quad (7)$$

For simplification, choose the input capacitor with an RMS current rating greater than half of the maximum load current.

The input capacitance value determines the input voltage ripple of the converter. If there is an input voltage ripple requirement in the system, choose the input capacitor that meets the specification.

The input voltage ripple can be estimated with Equation (8):

$$\Delta V_{IN} = \frac{I_{OUT}}{F_{SW} \times C_{IN}} \times \frac{V_{OUT}}{V_{IN}} \times (1 - \frac{V_{OUT}}{V_{IN}}) \quad (8)$$

The worst-case condition occurs at $V_{IN} = 2V_{OUT}$, shown in Equation (9):

$$\Delta V_{IN} = \frac{1}{4} \times \frac{I_{OUT}}{F_{SW} \times C_{IN}} \quad (9)$$

Selecting the Output Capacitor

An output capacitor is required to maintain the DC output voltage. Ceramic or POSCAP capacitors are recommended. The output voltage ripple can be estimated with Equation (10):

$$\Delta V_{OUT} = \frac{V_{OUT}}{F_{SW} \times L} \times (1 - \frac{V_{OUT}}{V_{IN}}) \times (R_{ESR} + \frac{1}{8 \times F_{SW} \times C_{OUT}}) \quad (10)$$

When using ceramic capacitors, the impedance at the switching frequency is dominated by the capacitance. The output voltage ripple is caused mainly by the capacitance. For simplification, the output voltage ripple can be estimated with Equation (11):

$$\Delta V_{OUT} = \frac{V_{OUT}}{8 \times F_{SW}^2 \times L \times C_{OUT}} \times (1 - \frac{V_{OUT}}{V_{IN}}) \quad (11)$$

The output voltage ripple caused by ESR is very small and therefore requires an external ramp to stabilize the system. The external ramp can be generated through resistor R4 and capacitor C4.

In the case of POSCAP capacitors, the ESR dominates the impedance at the switching frequency. The ramp voltage generated from the ESR dominates the output ripple. The output ripple can be approximated with Equation (12):

$$\Delta V_{OUT} = \frac{V_{OUT}}{F_{SW} \times L} \times (1 - \frac{V_{OUT}}{V_{IN}}) \times R_{ESR} \quad (12)$$

The maximum output capacitor limitation should be also considered in the design application. The MP2329C has a soft-start time period of around 1.6ms. If the output capacitor value is too high, then the output voltage cannot reach the design value during the soft-start time and will fail to regulate. The maximum output capacitor value (C_{O_MAX}) can be limited approximately with Equation (13):

$$C_{O_MAX} = (I_{LIM_AVG} - I_{OUT}) \times T_{ss} / V_{OUT} \quad (13)$$

Where I_{LIM_AVG} is the average start-up current during the soft-start period, and T_{ss} is the soft-start time.

Selecting the Inductor

The inductor is necessary for supplying constant current to the output load while being driven by the switched input voltage. A larger-value inductor results in less ripple current and a lower output ripple voltage but also has a larger physical footprint, higher series resistance, and lower saturation current. A good rule for determining the inductance value is to design the peak-to-peak ripple current in the inductor to be in the range of 30 - 50% of the maximum output current and ensure that the peak inductor current is below the maximum switch current limit. The inductance value can be calculated with Equation (14):

$$L = \frac{V_{OUT}}{F_{SW} \times \Delta I_L} \times (1 - \frac{V_{OUT}}{V_{IN}}) \quad (14)$$

Where ΔI_L is the peak-to-peak inductor ripple current. The inductor should not saturate under the maximum inductor peak current, including short current. I_{sat} should be $>9A$.

MPS inductors are optimized and tested for use with our complete line of integrated circuits.

Table 2 lists our power inductor recommendations. Select a part number based on your design requirements.

Table 2: Power Inductor Selection

Part Number	Inductor Value	Manufacturer
Select family series (MPL-AL)	1.5 μ H to 3.3 μ H	MPS
MPL-AL6050-1R5	1.5 μ H	MPS
MPL-AL6050-2R2	2.2 μ H	MPS
MPL-AL6050-3R3	3.3 μ H	MPS

Visit MonolithicPower.com under Products > Inductors for more information.

PCB Layout Guideline

Efficient PCB layout is critical for stable operation. For best results, refer to Figure 10 and follow the guidelines below. A four-layer layout is recommended for better thermal performance.

1. Place the high-current paths (GND, VIN, SW) very close to the device with short, direct, and wide traces.
2. Place the input capacitors as close to VIN and GND as possible.
3. Place the decoupling capacitor as close to VCC and GND as possible.
4. Keep the switching node SW short and away from the feedback network.
5. Keep the BST voltage path as short as possible.
6. Keep the VIN and GND pads connected with large coppers to achieve better thermal performance.
7. Add several vias close to the VIN and GND pads to help with thermal dissipation.

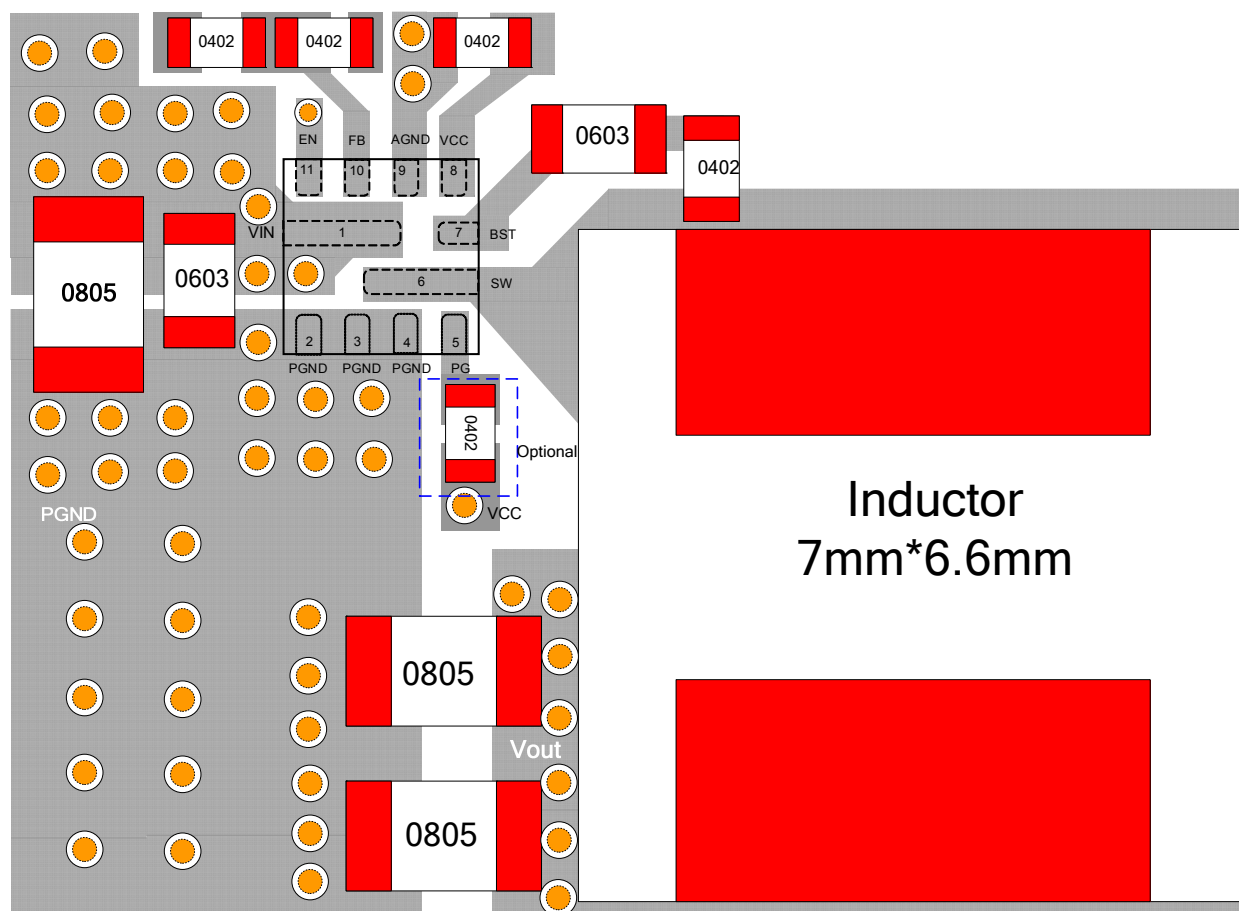


Figure 8: Recommended Layout

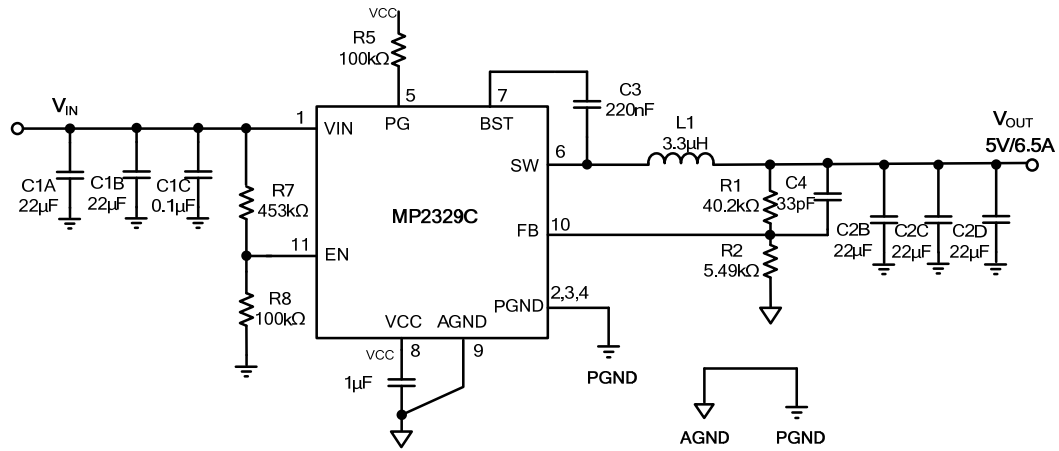
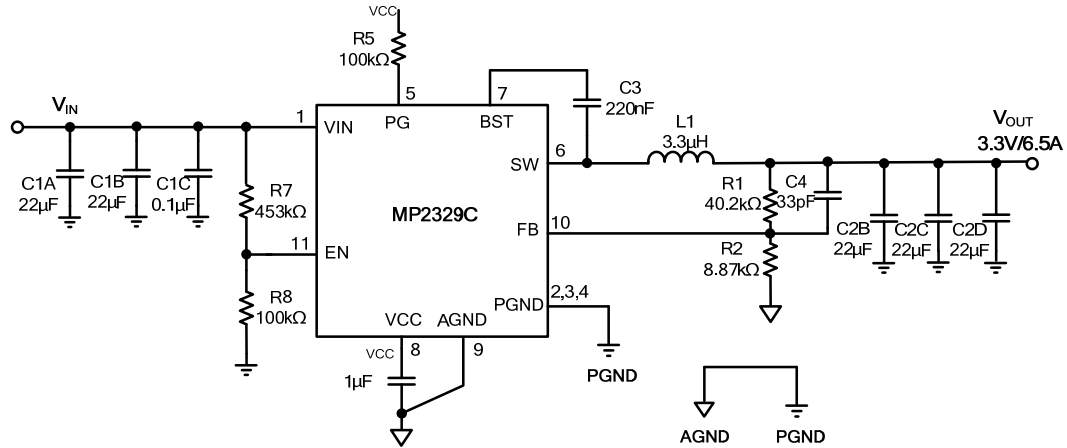
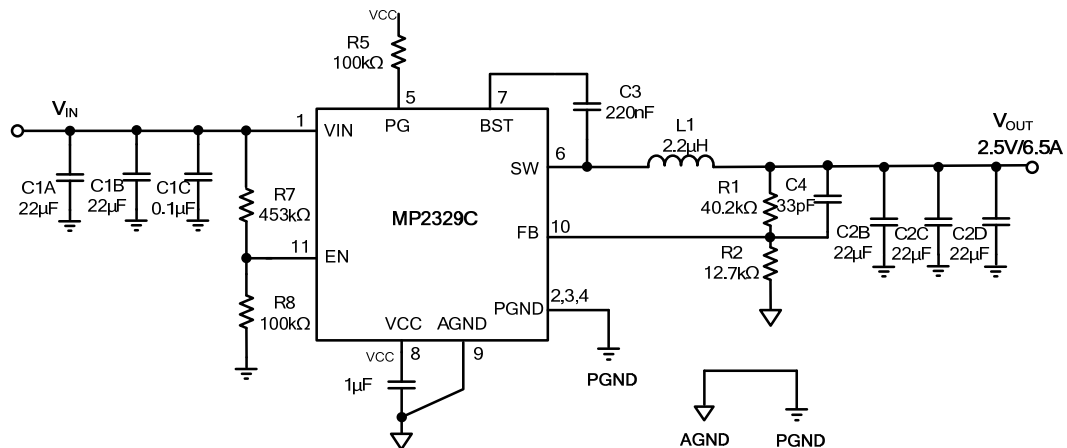
Design Example

Table 3 shows a design example when ceramic capacitors are applied.

Table 3: Design Example

V_{IN}	8V to 24V
V_{OUT}	3.3V
I_{OUT}	6.5A

The detailed application schematics are shown in Figure 9 through Figure 15. The typical performance and waveforms are shown in the Typical Characteristics section. For more devices applications, please refer to the related evaluation board datasheet.

TYPICAL APPLICATION CIRCUITS (10)

Figure 9: $V_{IN} = 19V$, $V_{OUT} = 5V/6.5A$

Figure 10: $V_{IN} = 19V$, $V_{OUT} = 3.3V/6.5A$

Figure 11: $V_{IN} = 19V$, $V_{OUT} = 2.5V/6.5A$

TYPICAL APPLICATION CIRCUITS ⁽¹⁰⁾ (continued)

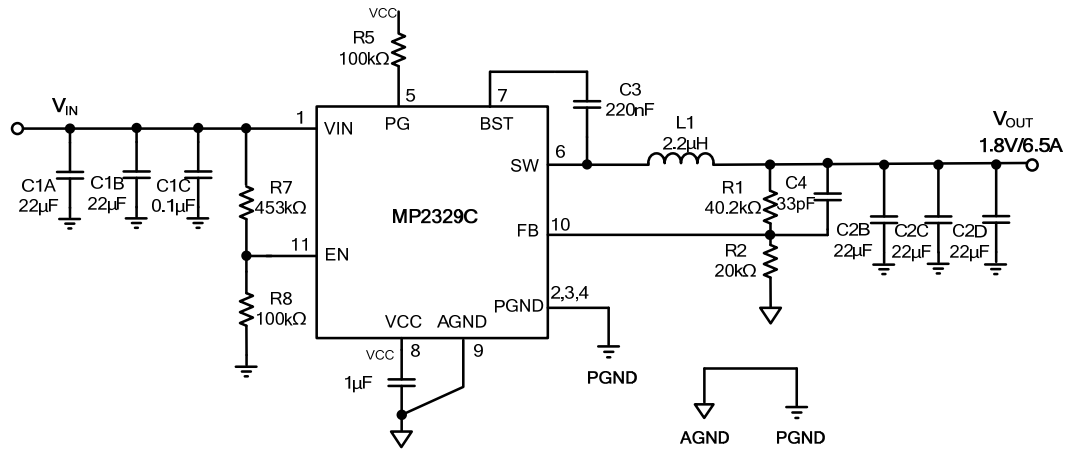


Figure 12: $V_{IN} = 19V$, $V_{OUT} = 1.8V/6.5A$

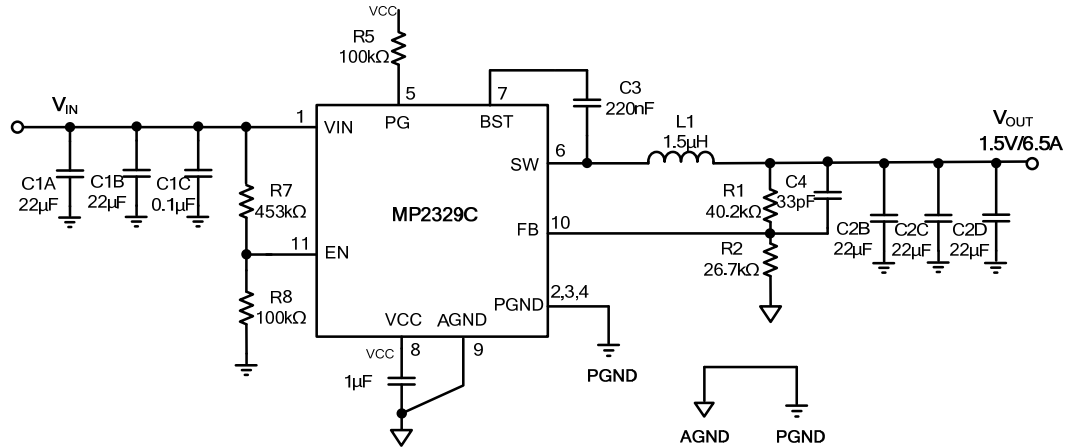


Figure 13: $V_{IN} = 19V$, $V_{OUT} = 1.5V/6.5A$

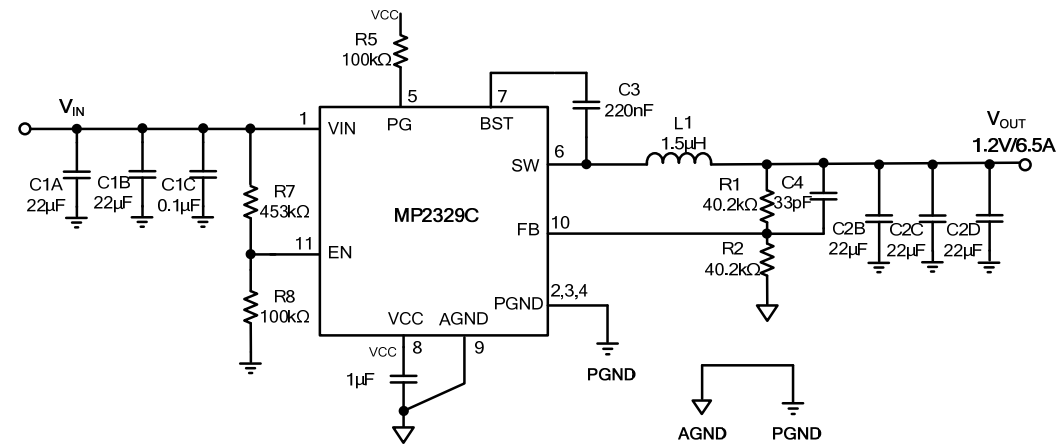


Figure 14: $V_{IN} = 19V$, $V_{OUT} = 1.2V/6.5A$

TYPICAL APPLICATION CIRCUITS ⁽¹⁰⁾ (continued)

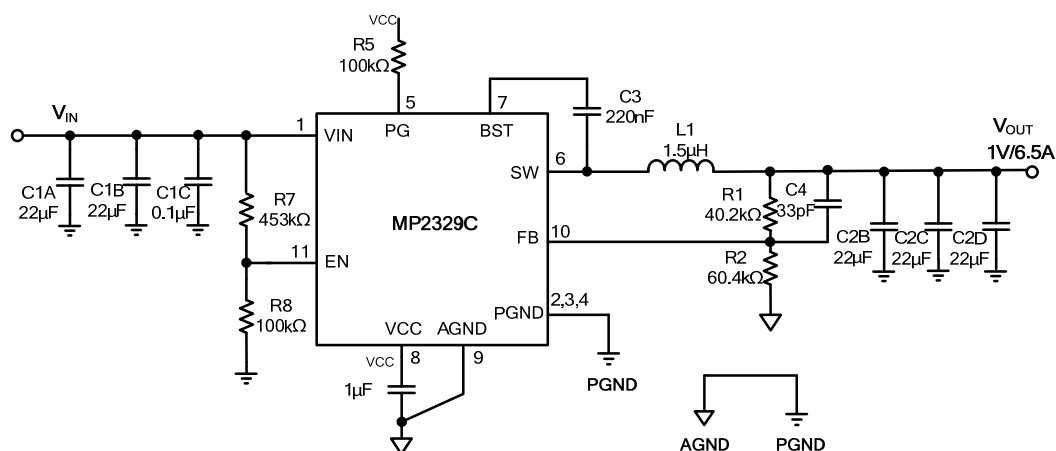


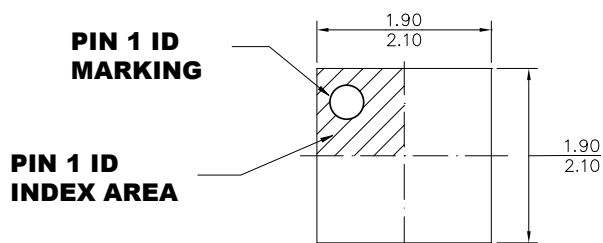
Figure 15: $V_{IN} = 19V$, $V_{OUT} = 1V/6.5A$

NOTE:

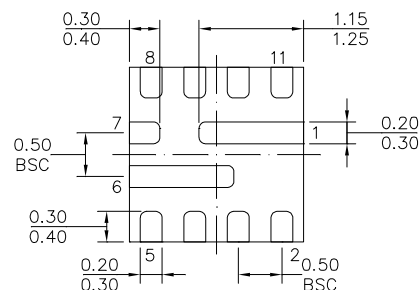
10) The EN resistor divider sets the VIN threshold to 7.5V. For 5V input applications, change the EN resistor accordingly.

PACKAGE INFORMATION

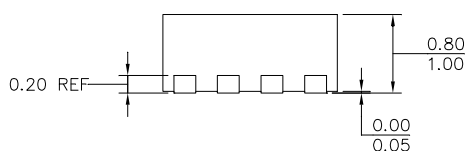
QFN-11 (2mmx2mm)



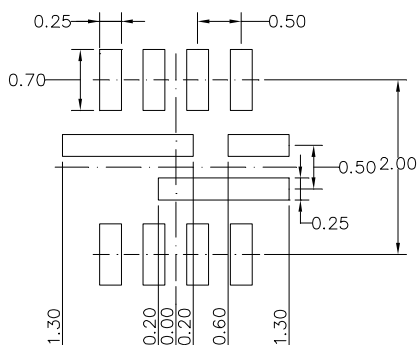
TOP VIEW



BOTTOM VIEW



SIDE VIEW

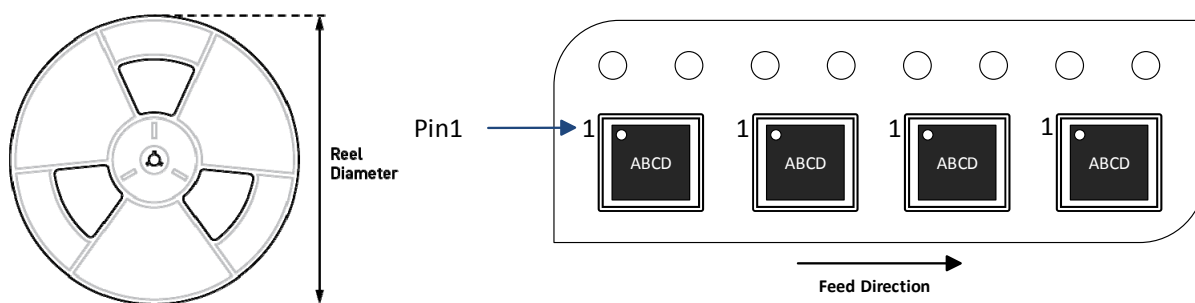


RECOMMENDED LAND PATTERN

NOTE:

- 1) LAND PATTERNS OF PIN1 AND PIN6 HAVE THE SAME LENGTH AND WIDTH
- 2) ALL DIMENSIONS ARE IN MILLIMETERS.
- 3) LEAD COPLANARITY SHALL BE 0.10 MILLIMETERS MAX.
- 4) JEDEC REFERENCE IS MO-220, VARIATION VCCD.
- 5) DRAWING IS NOT TO SCALE.

CARRIER INFORMATION



Part Number	Package Description	Quantity/Reel	Quantity/Tube	Reel Diameter	Carrier Tape Width	Carrier Tape Pitch
MP2329CGG-Z	QFN-11 (2mmx2mm)	5000	N/A	13in.	12mm	8mm

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